

Search:

L4	an	·		Refine Search
		Recall Text 👄	Clear	

Search History

DATE: Wednesday, October 01, 2003 Printable Copy Create Case

Set Nam side by sid		Hit Count	Set Name result set
DB=U	SPT; PLUR=YES; OP=ADJ		
<u>L4</u>	L3 and correlation	3	<u>L4</u>
<u>L3</u>	L2 and (detecting near2 signal)	89	<u>L3</u>
<u>L2</u>	L1 and (thin adj film)	5439	<u>L2</u>
Ll	thickness near2 (reducing or reduced)	41691	L1

END OF SEARCH HISTORY



L4: Entry 1 of 3

File: USPT

Oct 8, 2002

US-PAT-NO: 6462538

DOCUMENT-IDENTIFIER: US 6462538 B2

TITLE: Eddy current detection type thin film electrical resistance

meter

DATE-ISSUED: October 8, 2002

INVENTOR-INFORMATION:

NAME CITY

STATE ZIP CODE COU

COUNTRY

Harada; Yoshinori

Kashihara

JΡ

US-CL-CURRENT: 324/224; 324/222, 324/225, 324/230, 324/234,

324/765, 427/8, 438/10, 438/17

WEST

Generate Collection Print

L4: Entry 2 of 3

File: USPT

Aug 7, 2001

US-PAT-NO: 6271047

DOCUMENT-IDENTIFIER: US 6271047 B1

TITLE: Layer-thickness detection methods and apparatus for wafers

and the like, and polishing apparatus comprising same

DATE-ISSUED: August 7, 2001

INVENTOR-INFORMATION:

NAME CITY STATE ZIP CODE COUNTRY

Ushio; Yoshijiro Yohama JP Ueda; Takehiko Tokyo JP

US-CL-CURRENT: 438/14; 257/E21.528, 257/E21.53, 438/16, 451/41,

451/59, 451/6, 451/8



End of Result Set

Generate Collection Print

L4: Entry 3 of 3

File: USPT

May 7, 1996

US-PAT-NO: 5514452

DOCUMENT-IDENTIFIER: US 5514452 A

TITLE: Magnetic multilayer film and magnetoresistance element

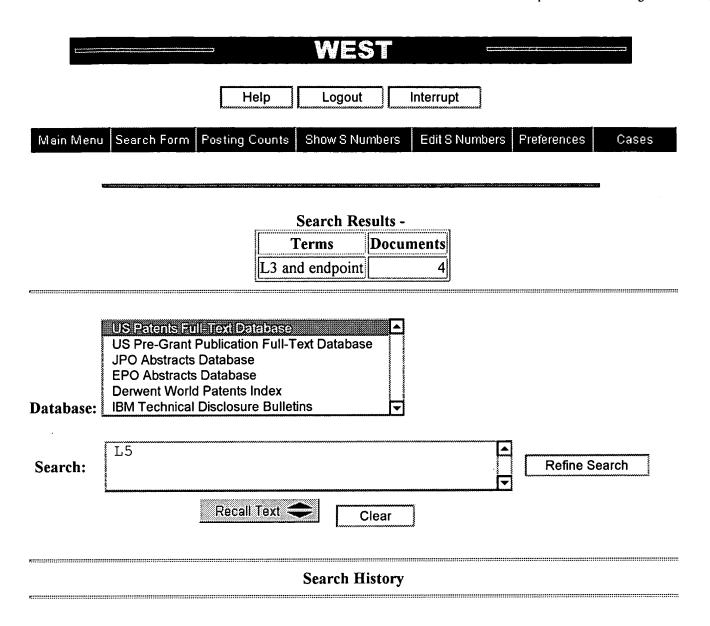
DATE-ISSUED: May 7, 1996

INVENTOR-INFORMATION:

NAME CITY STATE ZIP CODE COUNTRY

Araki; Satoru Chiba JP Miyauchi; Daisuke Chiba JP

US-CL-CURRENT: 428/213; 257/E43.005, 324/252, 360/110, 360/324, 428/216, 428/692, 428/693, 428/694R, 428/694T, 428/694TM, 428/900



DATE: Wednesday, October 01, 2003 Printable Copy Create Case

Set Name side by side		Hit Count	Set Name result set
DB=U	SPT; PLUR=YES; OP=ADJ		
<u>L5</u>	L3 and endpoint	4	<u>L5</u>
<u>L4</u>	L3 and correlation	3	<u>L4</u>
<u>L3</u>	L2 and (detecting near2 signal)	89	<u>L3</u>
<u>L2</u>	L1 and (thin adj film)	5439	<u>L2</u>
<u>L1</u>	thickness near2 (reducing or reduced)	41691	<u>L1</u>

END OF SEARCH HISTORY

WEST

Generate Collection

Print

Search Results - Record(s) 1 through 4 of 4 returned.

1. Document ID: US 6621264 B1

L5: Entry 1 of 4

File: USPT

Sep 16, 2003

US-PAT-NO: 6621264

DOCUMENT-IDENTIFIER: US 6621264 B1

TITLE: In-situ metalization monitoring using eddy current measurements during the process for removing the film

Full Title Citation Front Review Classification Date Reference Sequences Attachments Claims KWIC Draw, Desc Image

2. Document ID: US 6271047 B1

L5: Entry 2 of 4

File: USPT

Aug 7, 2001

US-PAT-NO: 6271047

DOCUMENT-IDENTIFIER: US 6271047 B1

TITLE: Layer-thickness detection methods and apparatus for wafers

and the like, and polishing apparatus comprising same

Full Title Citation Front Review Classification Date Reference Sequences Attachments Claims KWC Drava Desc Image

3. Document ID: US 5949927 A

L5: Entry 3 of 4

File: USPT

Sep 7, 1999

US-PAT-NO: 5949927

DOCUMENT-IDENTIFIER: US 5949927 A

TITLE: In-situ real-time monitoring technique and apparatus for endpoint detection of thin films during chemical/mechanical

polishing planarization

Full Title Citation Front Review Classification Date Reference Sequences Attachments

KWIC

4. Document ID: US 5433651 A

L5: Entry 4 of 4

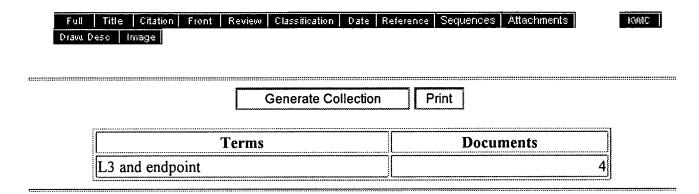
File: USPT

Jul 18, 1995

US-PAT-NO: 5433651

DOCUMENT-IDENTIFIER: US 5433651 A

TITLE: In-situ endpoint detection and process monitoring method and apparatus for chemical-mechanical polishing



Display Format: ΤI **Change Format**

> Previous Page Next Page